

# Low Energy Direct Contact Condenser Designs for Claus TGTUs in Desert Environments

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# Introduction

## ■ Tail Gas Unit :

- Hydrogenate Claus tail gas to  $H_2S$
- Cool hydrogenated tail gas in a Direct-Contact Condenser (DCC)
- Remove  $H_2S$  in a solvent (e.g. amine) contactor
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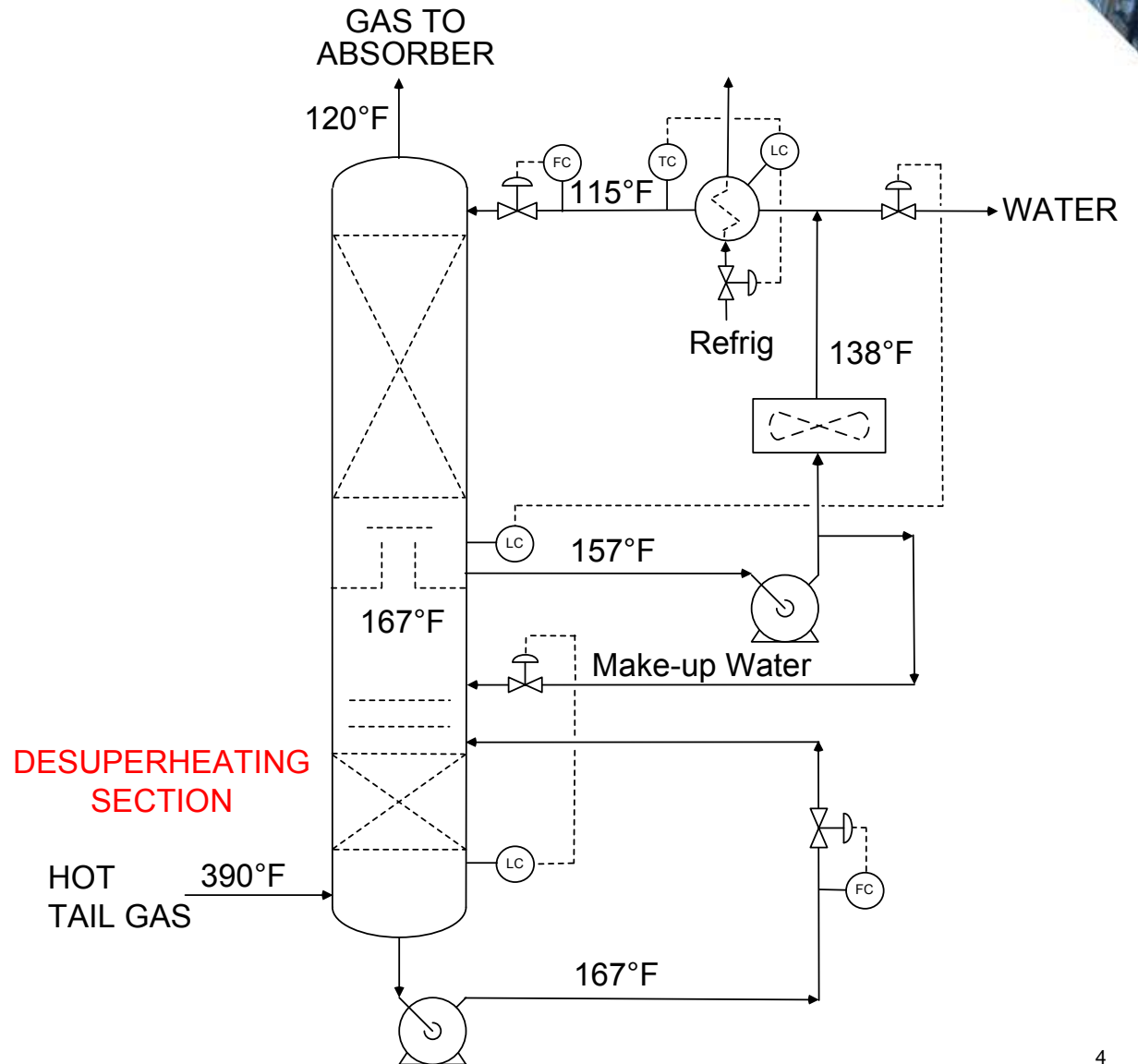
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## ■ Typical DCC Design:

- Single pumparound (PA) with 50% air cooling & 50% trim cooling
- Hot, arid regions require refrigeration for trim cooling
- High power and capital cost

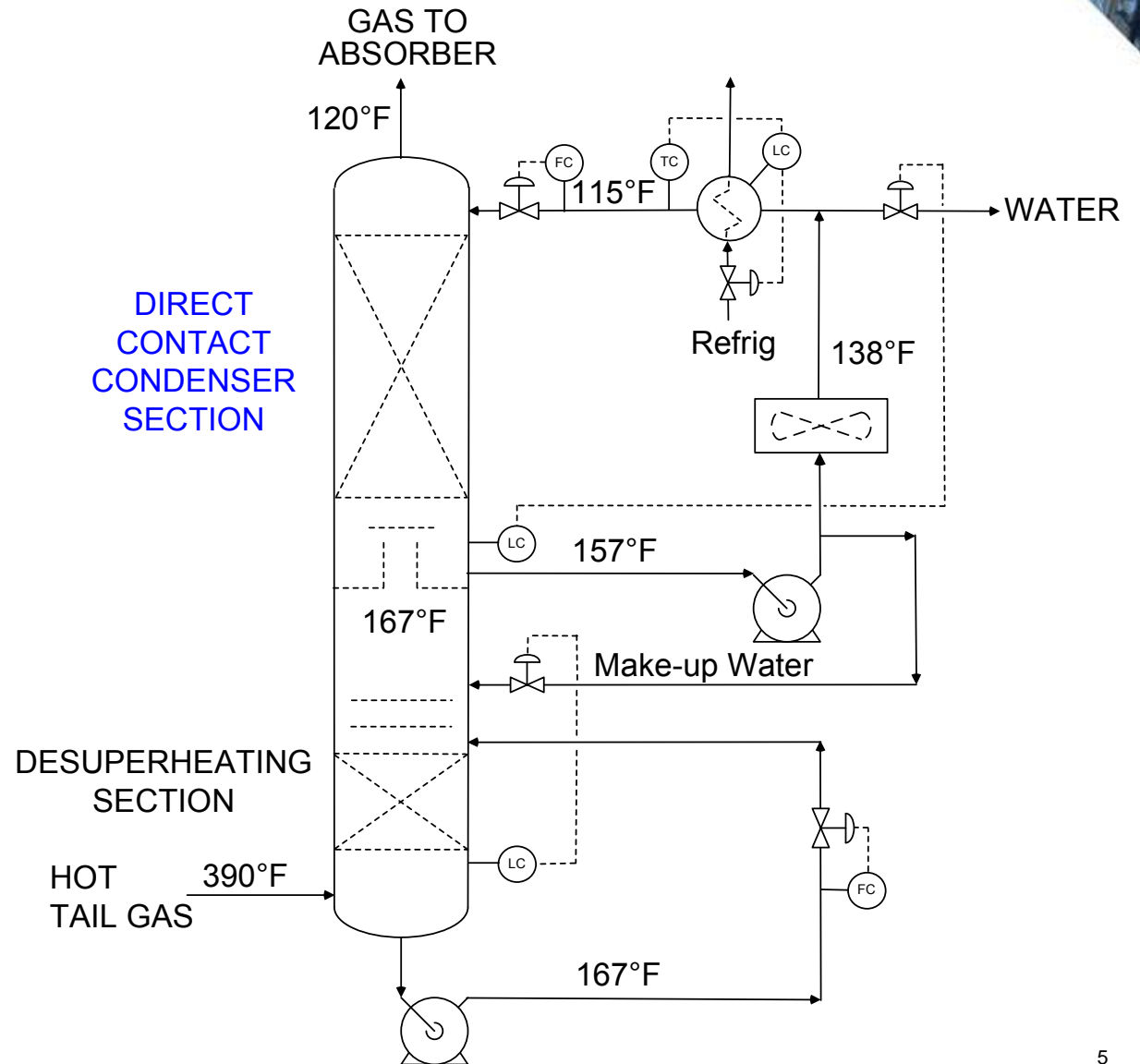
# Conventional DCC Process

- Hot tail gas desuperheated



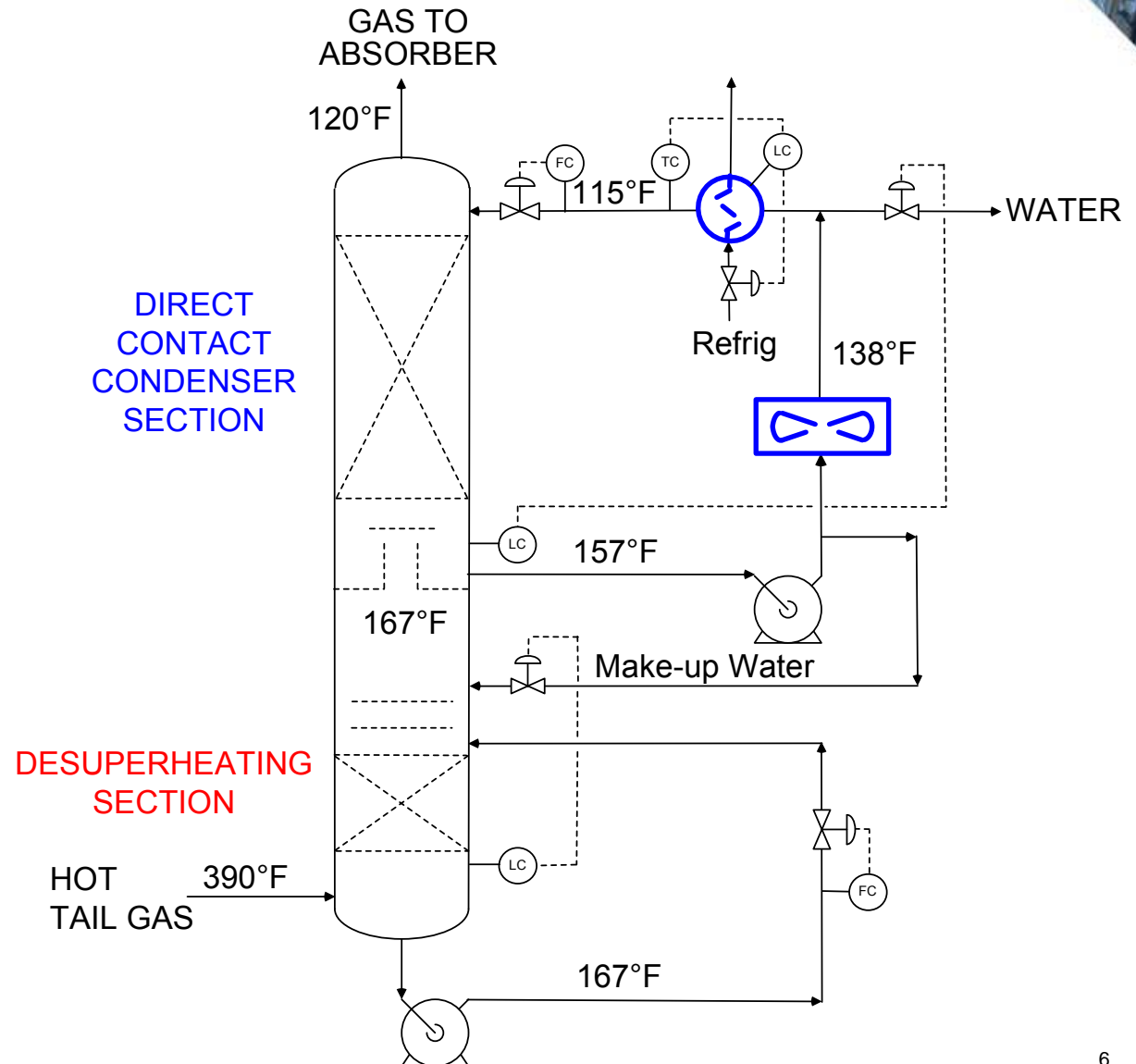
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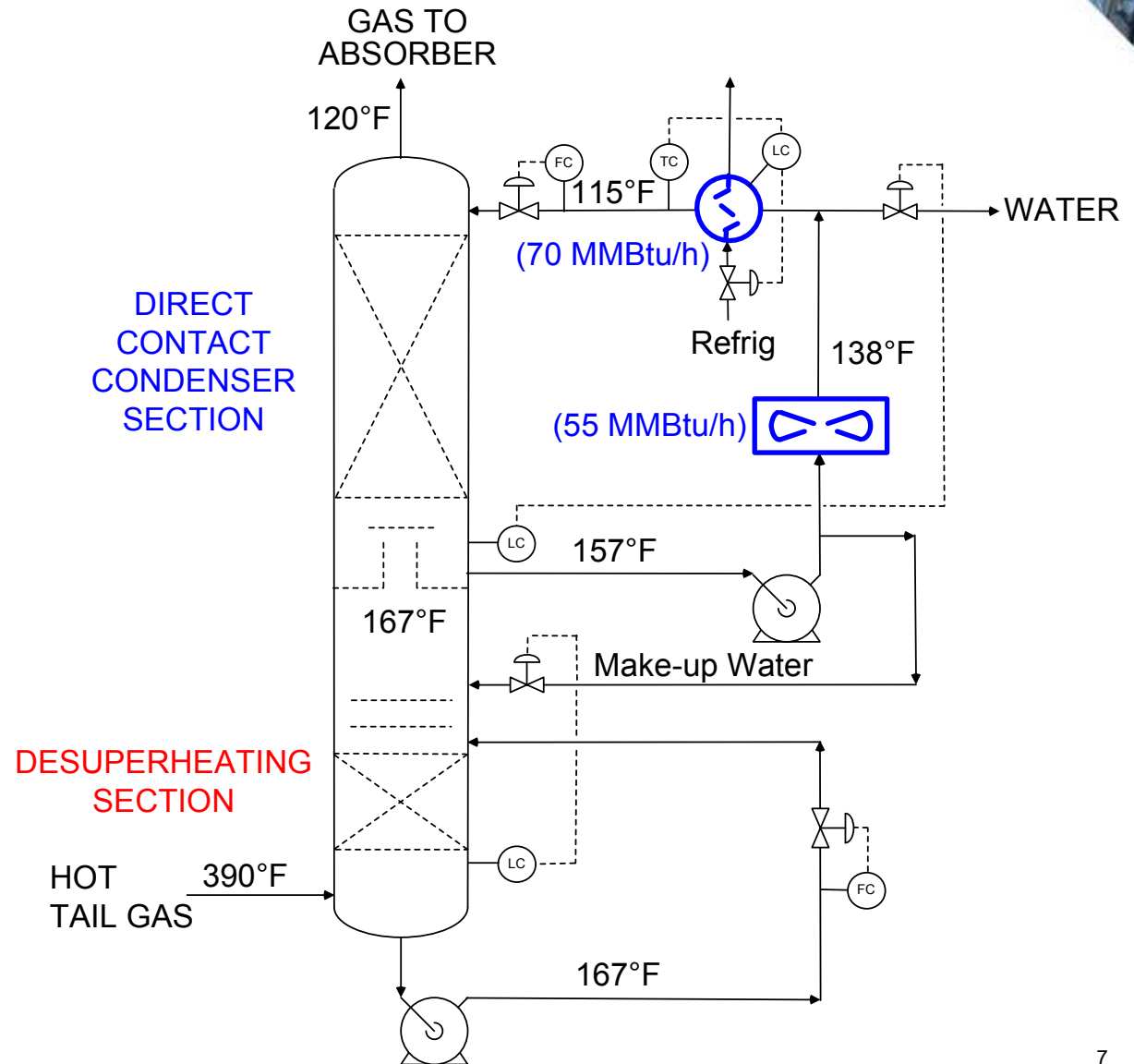
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## TO MINIMIZE...

- Target 5°F approach between effluent gas and process water inlet
- Target 95 - 115°F for process water inlet

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# DCC Optimization: Maximize Air Cooling

- Maximize air cooler size, duty
- But limited by air/process water approach, target 14 - 20°F
- For 122°F air, process water cooled to 138°F
- Rest of cooling by water
- But in arid areas, there is often no water!
- Need refrigeration for trim cooling ----- **Expensive!**
- Smaller approaches escalate air cooler size and cost with diminishing benefits



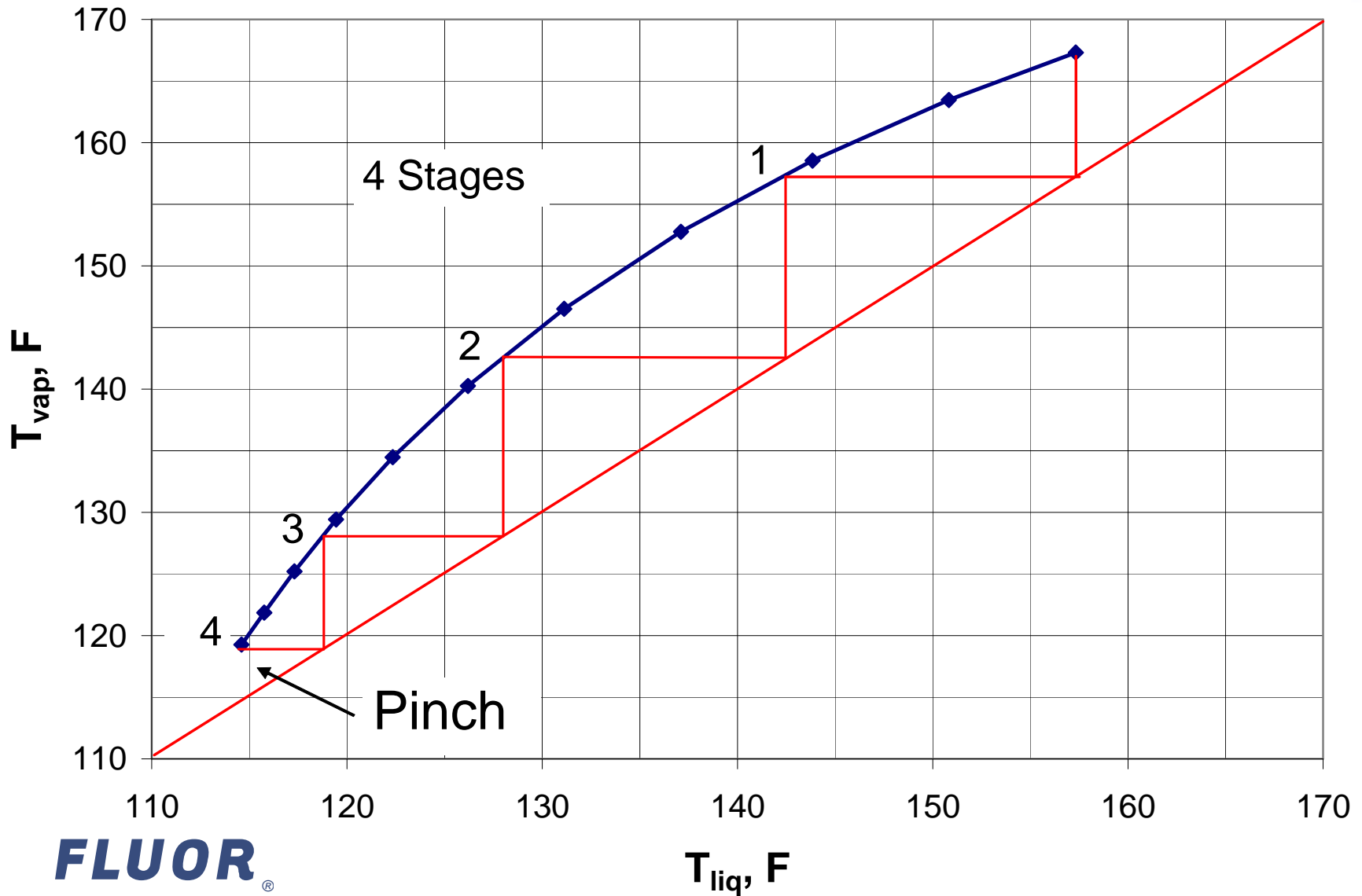
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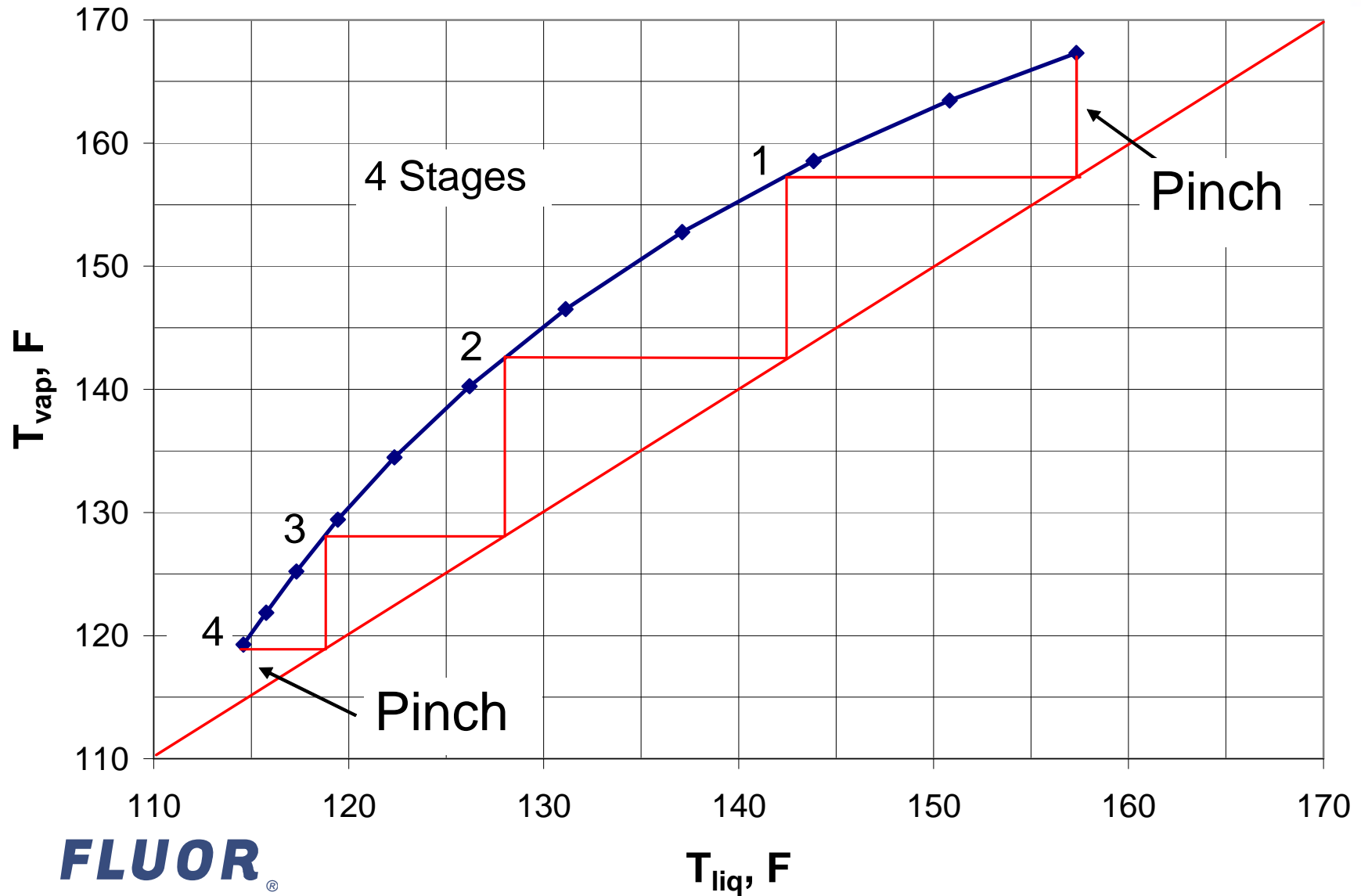
- Hotter process water
- Higher portion of duty can be removed by air
- Water T out of bed gets closer to gas T in
- Requires taller bed, expensive distributors
- More prone to maldistribution !
- Good practice: Keep (gas in) – (water out) >10°F

# Condenser Packed Bed Operation



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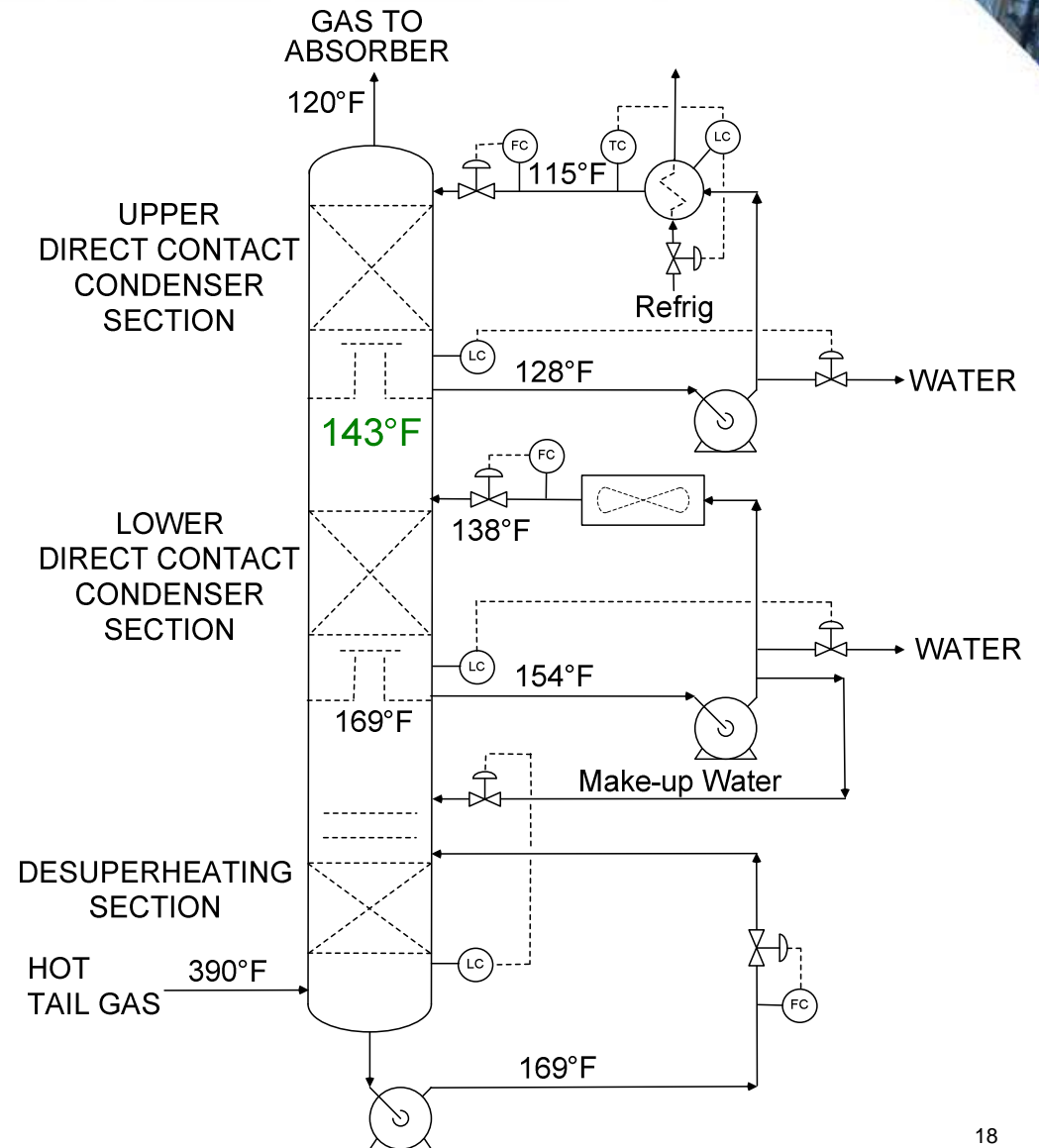


- Break into two pumparound circuits!

# FLUOR Invention: Improved DCC Process

## ■ Improved DCC Process

- Splits DCC bed into two, with separate PA circuits
  - Bottom circuit air cooled
  - Top circuit refrigerant or water-cooled
- **Refrig duty minimized!**

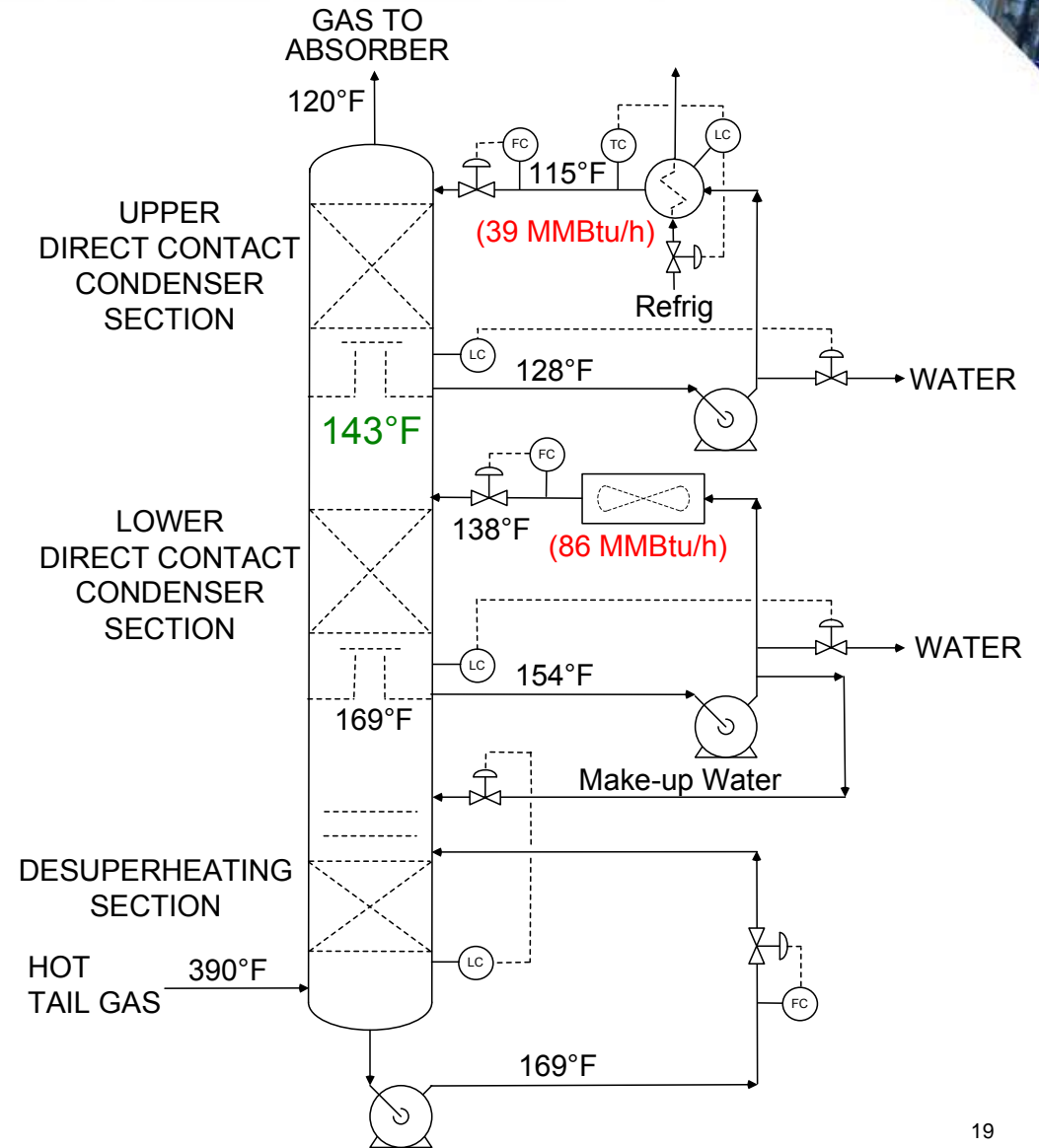


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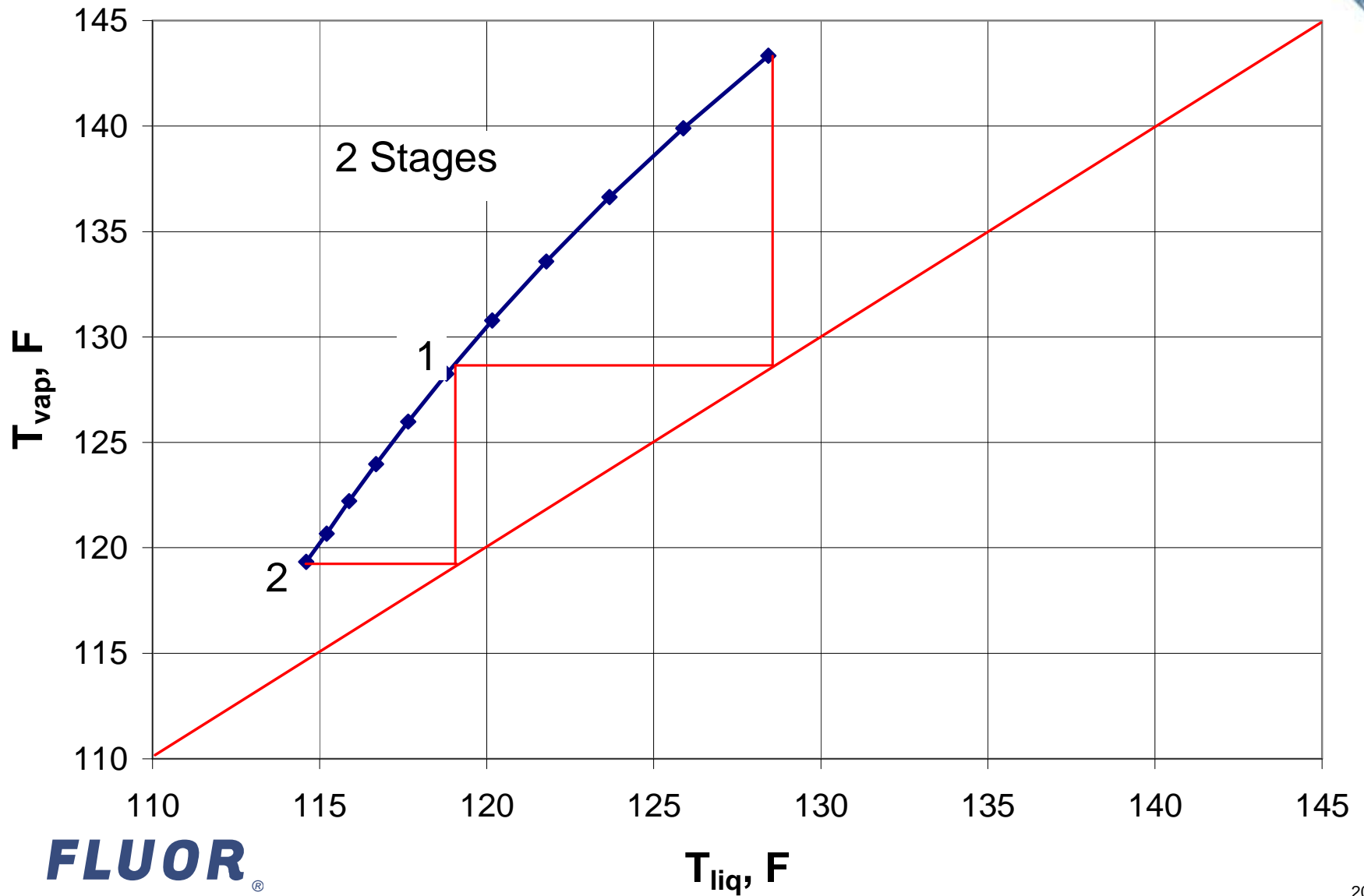
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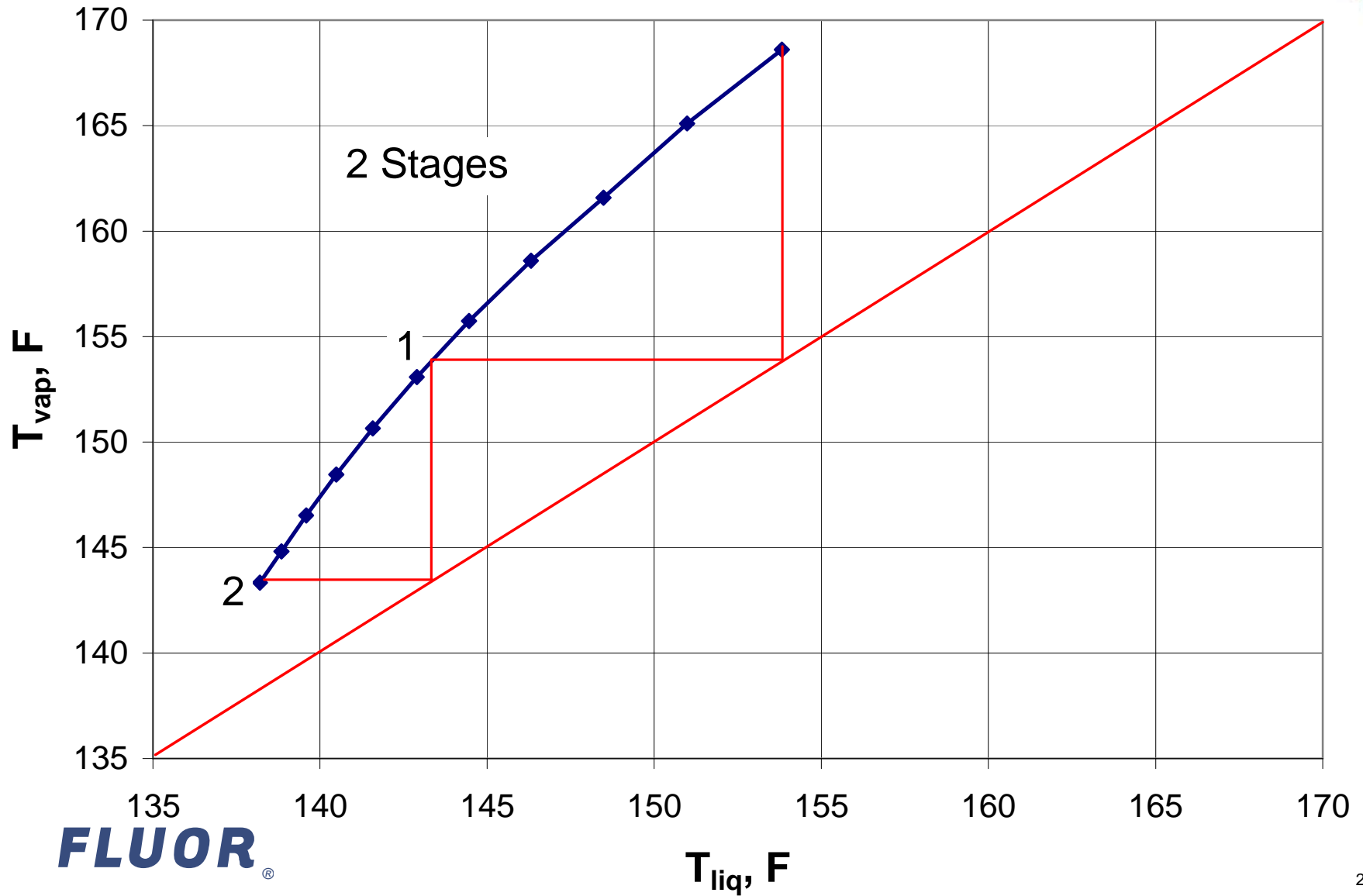
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# Upper Bed Operation

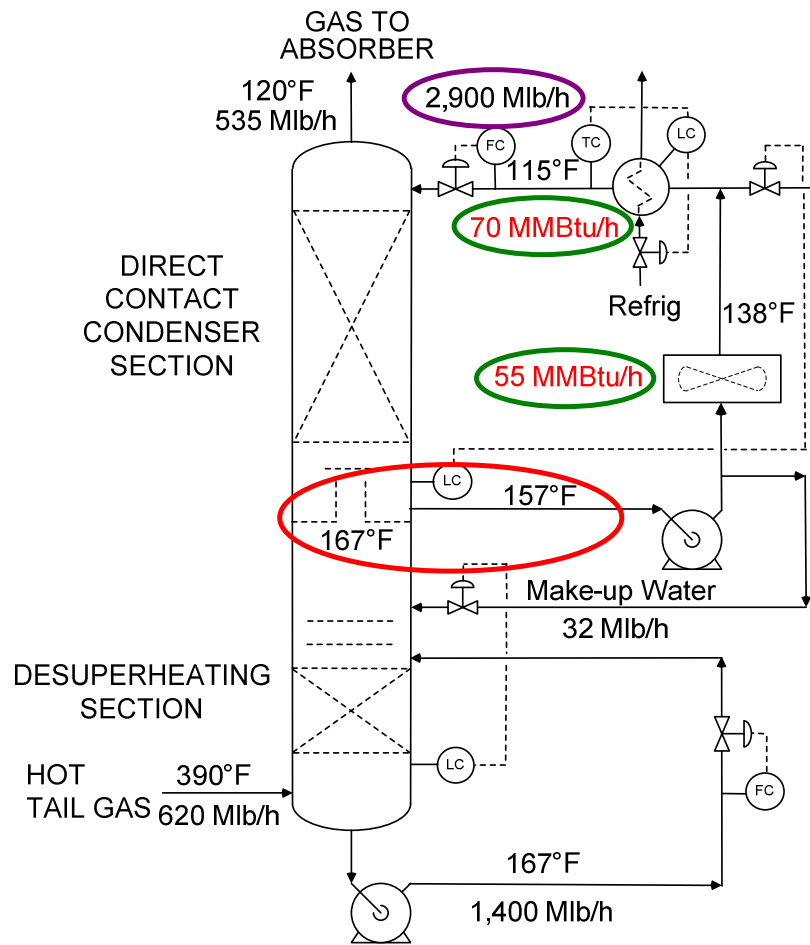


# Lower Bed Operation

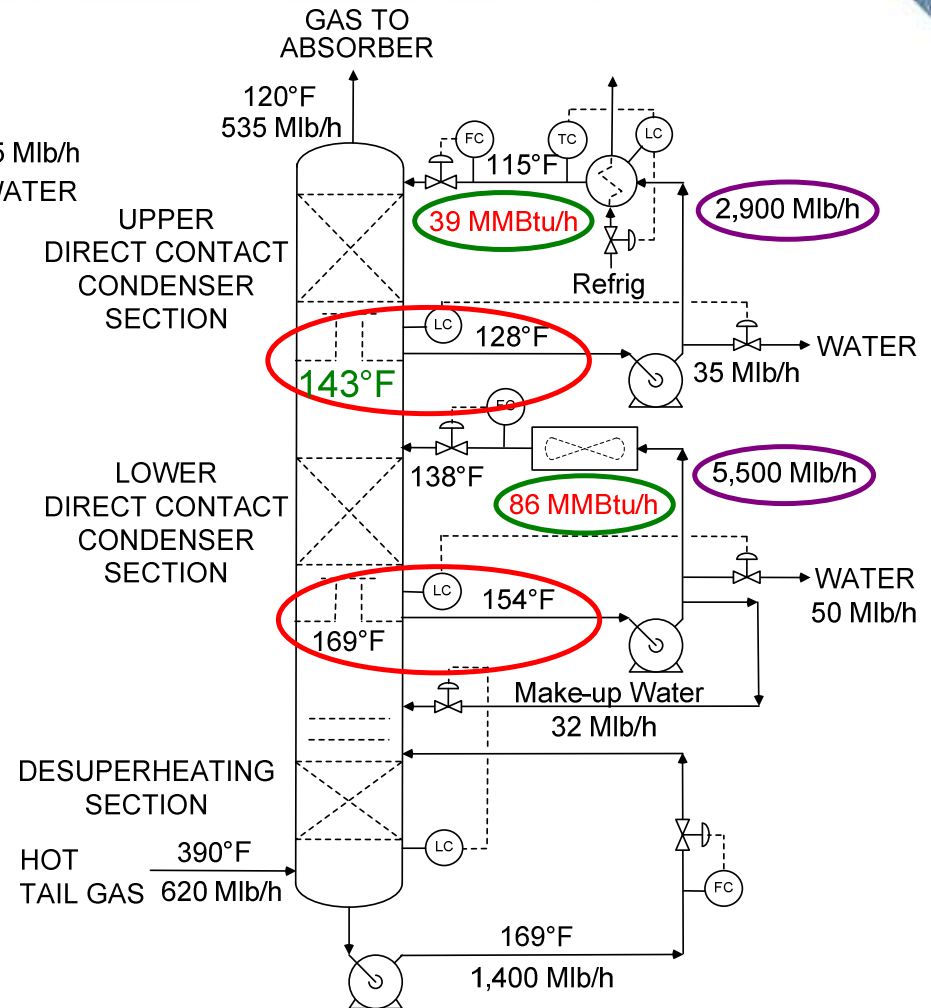


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# Economic Benefits of New DCC Process Scheme



CONVENTIONAL DESIGN



IMPROVED DESIGN

# Economic Benefits of New DCC Process Scheme

	Conventional Design	Improved Design
Capacity	Large Scale Middle East plant	Large Scale Middle East plant
Cooling Duty/Gas Rate/Gas Inlet and Outlet Temperature	Base	Base
Cooling Medium	Air + Propane Refrig	Air + Propane Refrig
Temperature Approach on Top of Bed	5°F	5°F
Temperature Approach on Bottom of Bed	10°F	15°F
Total Packing Height	Base	Slightly < Base

# Economic Benefits of New DCC Process Scheme

	Conventional Design	Improved Design
Column Internals Costs	Base	Slightly < Base
Tower Height & Diameter	Base	Same as Base
<b>Air Cooler Duty</b>	<b>55 MMBtu/h</b>	<b>86 MMBtu/h</b>
<b>Trim Cooler Duty</b>	<b>70 MMBtu/h</b>	<b>39 MMBtu/h</b>
Power Savings NPV <sup>1</sup>	Base	\$13 MM
Capital Cost Savings	Base	\$40 MM
Total Savings	Base	\$53 MM
Notes:		
1. NPV (net present value) based on 8% discount rate, \$24.5/MWh and 20 year plant life		



# Summary

- **Single PA DCCs in hot and arid regions lead to excessive capital and energy costs in trim cooling**
- **Fluor's patent pending DCC technology transfers as much as 50% of trim cooling duty to air coolers by utilizing two PA loops instead of one**
- **Resulting power and capital cost savings can be large**
- **As added benefit, two small packed beds instead of one large packed bed results in reliable, robust design**
- **Good process optimization can save energy and capital**

# Questions

## Sulfur Recovery Solutions by **FLUOR**<sup>®</sup>



Unique experience and knowledge in the design of sulfur recovery plants and tail gas treating units. A full range of services from feasibility studies to final start-up

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